

1.0A SURFACE MOUNT ULTRA-FAST RECTIFIER

Features

Glass Passivated Die Construction

Ultra-Fast Recovery Time for High Efficiency

Surge Overload Rating to 30A Peak

High Current Capability

Ideally Suited for Automated Assembly

Lead Free Finish/RoHS Compliant (Note 4)

Mechanical Data

Case: SMA

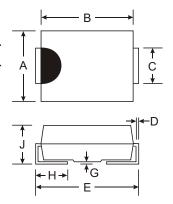
Case Material: Molded Plastic. UL Flammability Classification

Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020C Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3) Polarity: Cathode Band or Cathode Notch

Marking: Type Number & Date Code: See Page 3

Ordering Information: See Page 3 Weight: 0.064 grams (approximate)



SMA						
Dim	Min	Max				
Α	2.29	2.92				
В	4.00	4.60				
С	1.27	1.63				
D	0.15	0.31				
E	4.80	5.59				
G	0.10	0.20				
Н	0.76	1.52				
J	2.01	2.62				
All Dimensions in mm						

Maximum Ratings and Electrical Characteristics T_A = 25 C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _T = 75 C	lo	1.0					Α		
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load		30					Α		
Forward Voltage Drop @ I _F = 1.0A	V _{FM}		1.0		1.3		1.7		V
Peak Reverse Current @ T _A = 25 C at Rated DC Blocking Voltage (Note 5) @ T _A = 100 C		5.0 100				Α			
Reverse Recovery Time (Note 2)	t _{rr}		5	0			75		ns
Typical Total Capacitance (Note 1)	Ст		2	:0			10		pF
Typical Thermal Resistance, Junction to Terminal		30					C/W		
Operating and Storage Temperature Range		-65 to +150					С		

- Notes: 1. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$. See figure 5.
 - 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
 - 3. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pad as heat sink.
 - 4. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied, see EU Directive Annex Notes 5 and 7.
 - 5. Short duration pulse test used to minimize self-heating effect.



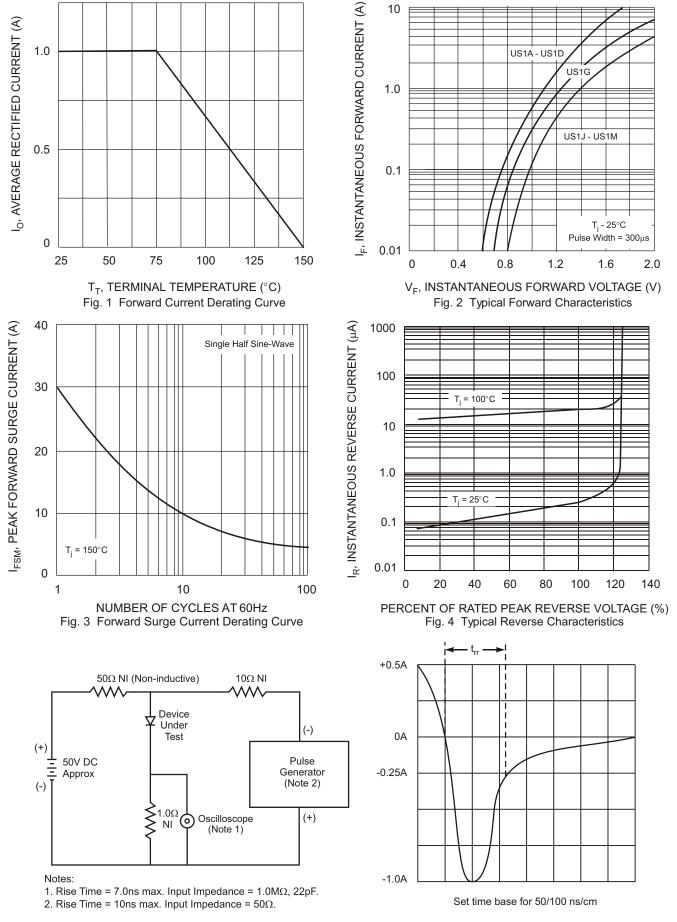


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit



Ordering Information (Note 6)

Device*	Packaging	Shipping
US1x-13-F	SMA	5000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



US1X = Product type marking code, ex. US1A
) ! != Manufacturers' code marking

YWW = Date code marking

Y = Last digit of year ex: 2 for 2002

WW = Week code 01 to 52

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